

Application Data Sheet
Application Information

Application type:: Regular
Subject matter:: Utility
CD-ROM or CD-R:: None
Number of CD disks:: None
Number of copies of CDs:: None
Sequence submission?::
Computer readable form (CRF)?:: No
Number of copies of CRF::
Title:: UNDER BUMP METALLIZATION
STRUCTURE OF A SEMICONDUCTOR WAFER
Attorney docket number:: HUANG 3261/EM
Request for early publication?:: No
Request for non-publication?:: No
Suggested drawing figure:: 2
Total drawing sheets:: 2
Small entity?:: No

Applicant Information

Applicant authority type:: Inventor
Primary citizenship country:: Taiwan, R.O.C.
Status: Full capacity
Given name:: Min-Lung
Middle name::
Family name:: HUANG
Name suffix::
City of Residence:: Kaohsiung, Taiwan 807, R.O.C.
State or province of residence::

Country of residence:: Taiwan, R.O.C.
Street of mailing address:: 10Fl., No. 8, Alley 2, Lane 33,
Dingyung St., Sanmin Chiu
City of mailing address:: Kaohsiung, Taiwan 807, R.O.C.
State or province of mailing
address::
Country of mailing address:: Taiwan, R.O.C.
Postal or zip code of mailing
address::

Correspondence Information

Correspondence customer number:: 23364
Phone number:: 703-683-0500
Fax number:: 703-683-1080
E-mail address:: mail@baconthomas.com

Representative Information

Representative customer number:: 23364

Domestic Priority Information

Application::	Continuity Type::	Parent Application::	Parent Filing Date::
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Foreign Priority Information

Country::	Application number::	Filing Date::	Priority claimed::
TAIWAN, R.O.C.	092117896	June 30, 2003	YES

Assignee Information

Assignee name::	Advanced Semiconductor Engineering, Inc.
Street of mailing address::	26 Chin 3rd Rd., Nantze Export Processing Zone
City of mailing address::	Kaoshiung
State or province of mailing address::	
Country of mailing address::	Taiwan, R.O.C.
Postal or zip code of mailing address::	